



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

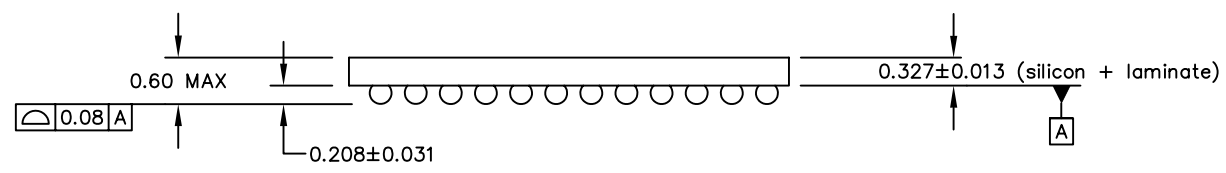
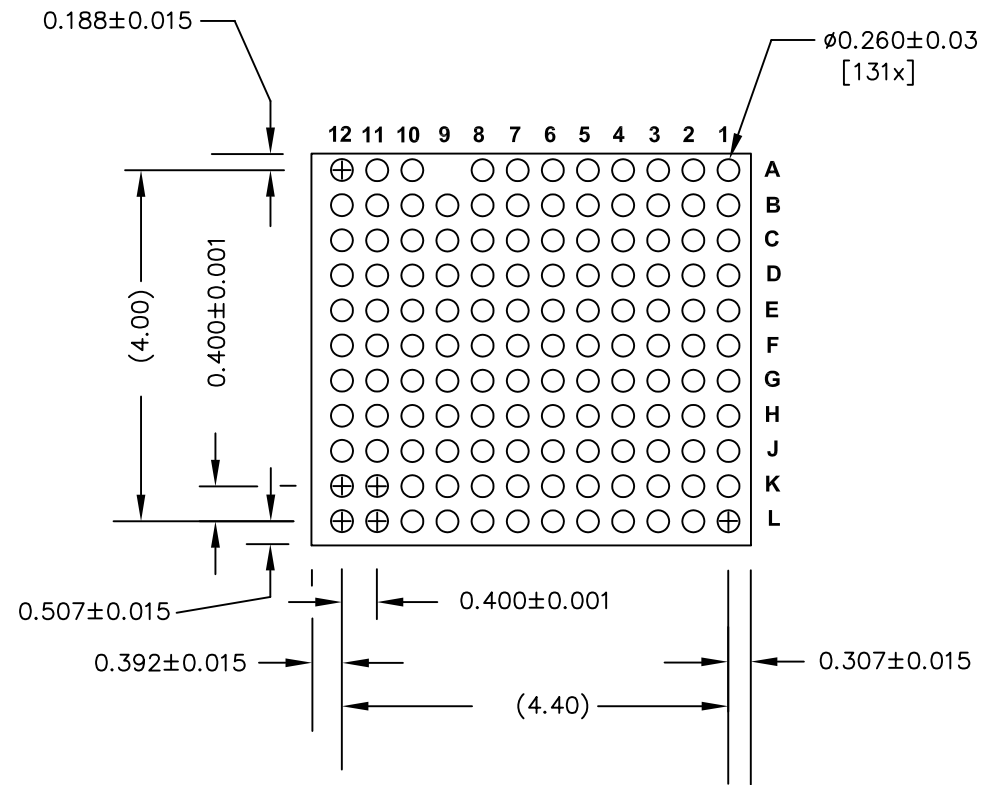
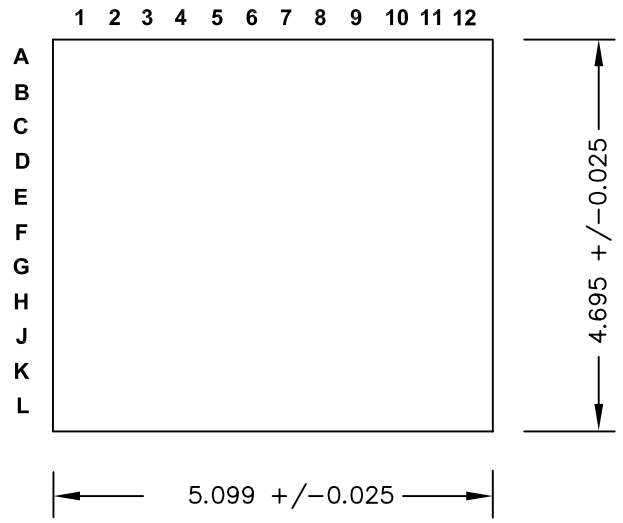
1 2 3 4 5 6

A


B

C

D



- Notes:
- (1) ALL DIMENSIONS ARE IN MM
 - (2) PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress Web
 - (3) JEDEC – Publication 95; Design Guide 4.18

 CYPRESS
Company Confidential

TITLE
PACKAGE OUTLINE, 131BALL BENICIA WLCSP 5.099X4.695X0.60 MM
FB131/FN131

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PACKAGE CODE(S)
FB131/FN131

SPEC NO. 001-62221 REV *C

SCALE: 1:1 SHEET 1 OF 2

1 2 3 4 5 6

Rev.	ECN No.	Origin of Change	Description of Change
**	2948725	MLA	NEW SPEC
*A	3055605	MLA	Revise length, width, silicon thickness, overall pkg height and ball offset. Add FB131 pkg code and package weight.
*B	3509897	MLA	Revise package weight statement. Revise 0.305 dimension to include 0.022 laminate thickness.
*C	4001719	MLQAD/ ROWI	Sunset review. Updated template. Changed title from PACKAGE OUTLINE, 131BALL BENICIA WLCSP, FB131/FN131 to PACKAGE OUTLINE, 131BALL BENICIA WLCSP 5.099X4.695X0.60 MM FB131/FN131.

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 131BALL BENICIA WLCSP 5.099X4.695X0.60 MM FB131/FN131	
SPEC NO. 001-62221	REV *C
SCALE: 1:1	SHEET 2 OF 2

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PACKAGE CODE(S)
FB131/FN131

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